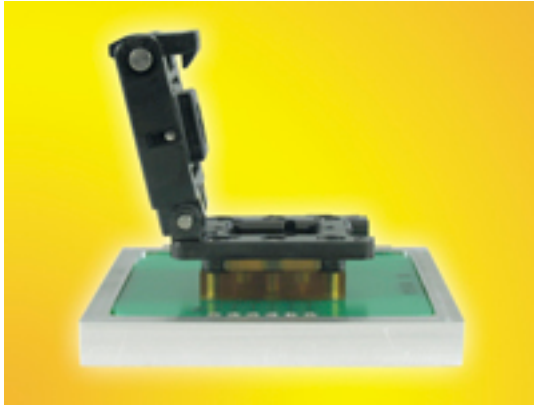


Stamped Spring Pin BGA Socket Addresses Burn-in Characterization



Ironwood Electronics recently introduced a BGA socket addressing burn-in characterization requirements for BGA devices - CBT-BGA-6011. The contactor is a stamped spring pin with 19-gram actuation force per ball and cycle life of 500,000 insertions. Low force eliminates ball sticking issues due to temperature testing. The self inductance of the contactor is 0.93 nH, insertion loss < 1 dB at 23.2 GHz, and contact resistance is <16mOhms. The current capacity of each contactor is 8 A at 80C temperature rise. Socket temperature range is -55C to +180C. The socket also features a floating guide for precise ball to pin alignment. The specific configuration of the package to be tested in the CBT-BGA-6011 is a BGA, 9 mm x12 mm, 1 mm pitch, 48-position, 9x11 ball array. The socket is mounted using supplied hardware on the target PCB with no soldering, and uses smallest footprint for nearby passive components. To use, place the BGA device into the socket base and close the socket lid assembly on to the base using the latch. This socket uses spring loaded compression mechanism for precise actuation. It can be used for hand test and burn-in characterization as well as production burn-in using automated chip loading and un-loading.

Ironwood Electronics

800-404-0204, www.ironwoodelectronics.com [1]

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